

Annex 5: HW change description v1.2 to Test Report 20-1-0017102T03a-C01-A5



Deutsche
Akkreditierungsstelle
D-PL-12047-01-01
D-PL-12047-01-03
D-PL-12047-01-04

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Testing company:	CETECOM GmbH Im Teelbruch 116 45219 Essen Germany Tel. + 49 (0) 20 54 / 95 19-0 Fax: + 49 (0) 20 54 / 95 19-150	Applicant:	SICK AG
Test Object / Tested Device(s):	UWB Tag LOCU111-0020		
FCC ID:	WRMLOCU1	IC:	10066A-LOCU1
Testing has been carried out in accordance with:	Title 47 CFR, Chapter I FCC Regulations, Subchapter A §15.250 ISED-Regulations RSS-Gen, Issue 5 RSS-220, Issue 1, Amendment 1 Deviations, modifications or clarifications (if any) to above mentioned documents are written in each section under "Test method and limit".		



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1 LOCU1xxx HW change description v1.2



Hardware change description
SICK LOCU1xx – UWB TAG

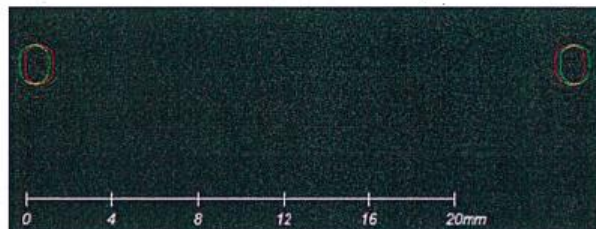
v1r3 -> v1r3.1 change description

Improvements/changes:

- v1r3.1 is a minor revision of v1r3 with improved coin battery holder.
- BOMs for all variants are equal for both v1r3 and v1r3.1 with a single exception: The only difference is for LOCU Battery Basic/Advanced assembly variant, where there is additional plate for negative battery contact (Keystone 2991).
- Revision label on the bottom side of PCB was changed for all variants.

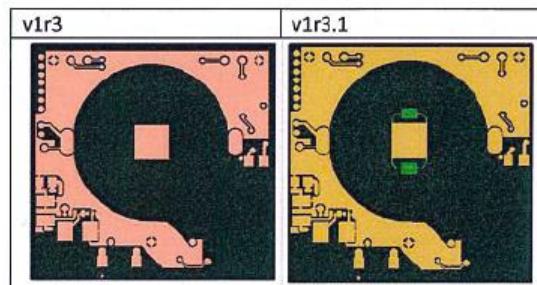
Details for changes of LOCU Battery Basic/Advanced bottom layer:

1. Battery holder: Pad adjustment of negative battery contact- milled grooves for battery holder are shifted in v1r3.1 comparing to v1r3. The pitch of grooves is increased by 0,45 mm.



- red mark - v1r3
- green mark - v1r3.1

2. Negative battery contact: Additional negative battery contact (Keystone 2991) added to v1r3.1:



RF performance is not affected, since antennas are on top side of the PCB, which is shielded by ground plane in the inner layer from the slightly adjusted bottom layer.

Date and place: Hamburg, d. 16.10.20 i.A. Andreas Guenther
 Group Manager Electronics / Identification & Measuring
 Research & Development
 SICK AG
 Signature: i. A. Guenther

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